

8mm BI-COLOR INDICATOR LAMP

Part Number: WP799EGW

High Efficiency Red

Features

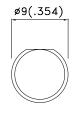
- UNIFORM LIGHT OUTPUT.
- LOW POWER CONSUMPTION.
- MILKY WHITE DIFFUSION LENS.
- 3 LEADS WITH ONE COMMON LEAD.
- I.C. COMPATIBLE.
- LONG LIFE SOLID STATE RELIABILITY.
- RoHS COMPLIANT.

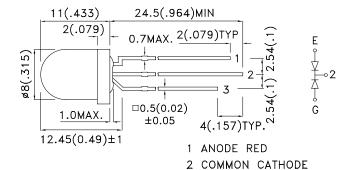
Description

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

The Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

Package Dimensions





3 ANODE GREEN

1. All dimensions are in millimeters (inches).

2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.

Lead spacing is measured where the lead emerge from the package.
 Specifications are subject to change without notice.





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Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
		,,	Min.	Тур.	201/2
WP799EGW	High Efficiency Red (GaAsP/GaP)	WHITE DIFFUSED	36	80	50°
WF799EGW	Green (GaP)	WHITE DIFFOSED	18	50	

- 1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value. 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	High Efficiency Red Green	627 565		nm	I==20mA
λD [1]	Dominant Wavelength	High Efficiency Red Green	625 568		nm	I==20mA
Δλ1/2	Spectral Line Half-width	High Efficiency Red Green	45 30		nm	I==20mA
С	Capacitance	High Efficiency Red Green	15 15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	High Efficiency Red Green	2 2.2	2.5 2.5	V	I==20mA
lR	Reverse Current	High Efficiency Red Green		10 10	uA	V _R = 5V

Notes:

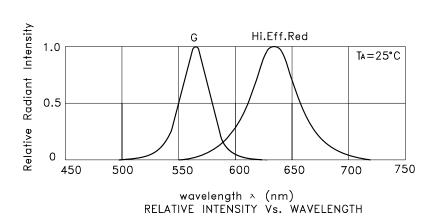
- 1.Wavelength: +/-1nm.
- 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

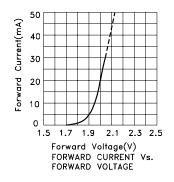
Parameter	High Efficiency Red	Green	Units		
Power dissipation	75	62.5	mW		
DC Forward Current	30	25	mA		
Peak Forward Current [1]	160	140	mA		
Reverse Voltage	ţ	V			
Operating / Storage Temperature	-40°C To +85°C				
Lead Solder Temperature [2]	260°C For 3 Seconds				
Lead Solder Temperature [3]	260°C For 5 Seconds				

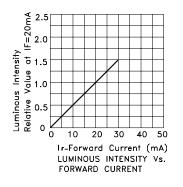
- 1. 1/10 Duty Cycle, 0.1ms Pulse Width.
- 2. 2mm below package base.
 3. 5mm below package base.

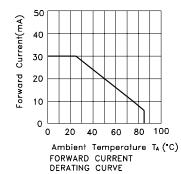
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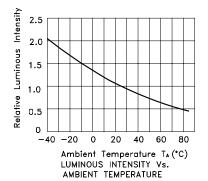


WP799EGW High Efficiency Red







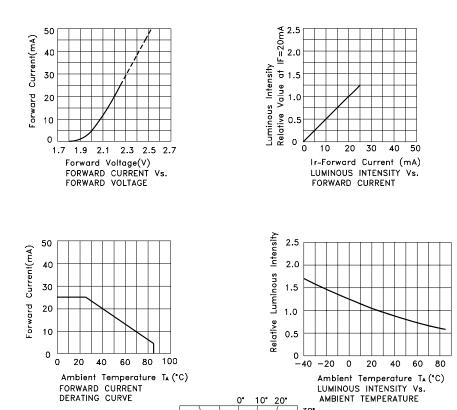


0° 10° 20°
30°
40°
50°
60°
70°
80°
90°
SPATIAL DISTRIBUTION

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Green

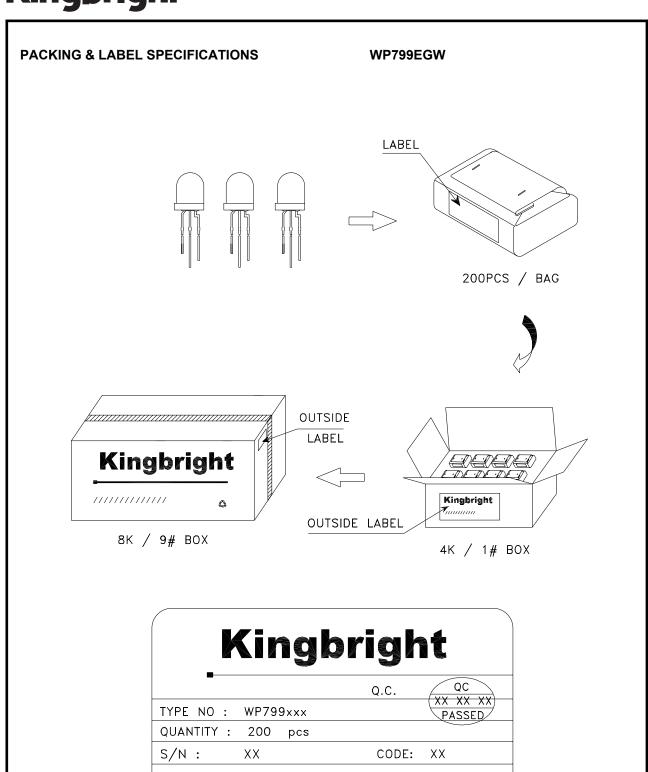


0.7 50° 60° 70° 80° 90° SPATIAL DISTRIBUTION

40°

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LOT NO:

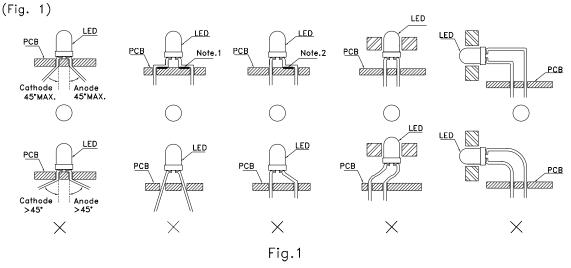
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RoHS Compliant

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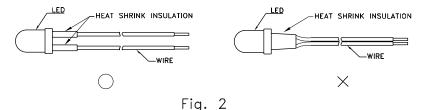
LED MOUNTING METHOD

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead—forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.

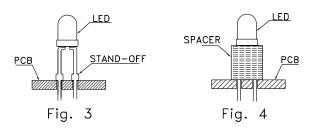


" \bigcirc " Correct mounting method " \times " Incorrect mounting method Note 1-2: Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.

2. When soldering wire to the LED, use individual heat—shrink tubing to insulate the exposed leads to prevent accidental contact short—circuit. (Fig. 2)



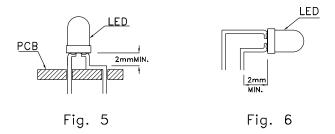
3. Use stand—offs (Fig. 3) or spacers (Fig. 4) to securely position the LED above the PCB.



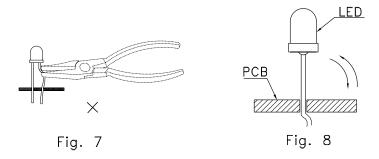
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LEAD FORMING PROCEDURES

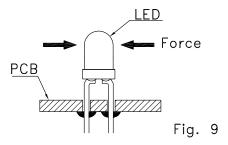
1. Maintain a minimum of 2mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)



- 2. Lead forming or bending must be performed before soldering, never during or after Soldering.
- 3. Do not stress the LED lens during lead—forming in order to fractures in the lens epoxy and damage the internal structures.
- 4. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)
- 5. Do not bend the leads more than twice. (Fig. 8)



6. After soldering or other high—temperature assembly, allow the LED to cool down to 50°C before applying outside force (Fig. 9). In general, avoid placing excess force on the LED to avoid damage. For any questions please consult with Kingbright representative for proper handling procedures.



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